

### LM3704/LM3705

# Microprocessor Supervisory Circuits with Power Fail Input, Low Line Output and Manual Reset

### **General Description**

The LM3704/LM3705 series of microprocessor supervisory circuits provide the maximum flexibility for monitoring power supplies and battery controlled functions in systems without backup batteries. The LM3704/LM3705 series are available in MSOP-10 and 9-bump micro SMD packages.

Built-in features include the following:

Reset: Reset is asserted during power-up, power-down, and brownout conditions.  $\overline{\text{RESET}}$  is guaranteed down to  $V_{CC}$  of 1.0V.

Manual Reset Input: An input that asserts reset when pulled low.

Power-Fail Input: A 1.225V threshold detector for power fail warning, or to monitor a power supply other than  $V_{\rm CC}$ .

Low Line Output: This early power failure warning indicator goes low when the supply voltage drops to a value which is 2% higher than the reset threshold voltage.

#### **Features**

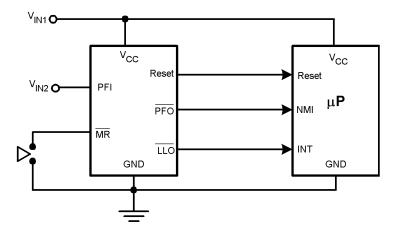
- Standard Reset Threshold voltage: 3.08V
- Custom Reset Threshold voltages: For other voltages between 2.2V and 5.0V in 10mV increments, contact National Semiconductor Corp.

- No external components required
- Manual-Reset input
- RESET (LM3704) or RESET (LM3705) outputs
- Precision supply voltage monitor
- Factory programmable Reset Timeout Delay
- Separate Power Fail comparator
- Available in micro SMD package for minimum footprint
- ±0.5% Reset threshold accuracy at room temperature
- ±2% Reset threshold accuracy over temperature extremes
- Reset assertion down to 1V V<sub>CC</sub> (RESET option only)
- 28 µA V<sub>CC</sub> supply current

### **Applications**

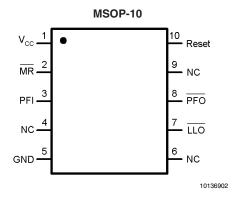
- Embedded Controllers and Processors
- Intelligent Instruments
- Automotive Systems
- Critical µP Power Monitoring

### **Typical Application**

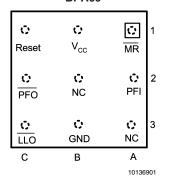


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# **Connection Diagram**



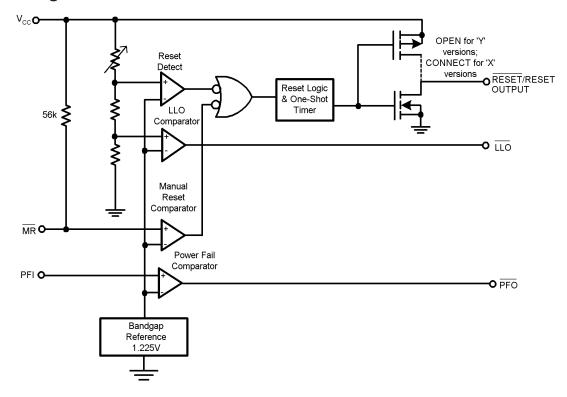
Top View (looking from the coating side) micro SMD 9 Bump Package BPA09



# **Pin Description**

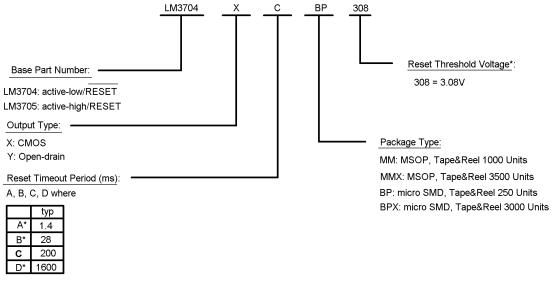
Pin	No.		
micro SMD	MSOP	Name	Function
A1	2	MR	Manual-Reset input. When $\overline{\text{MR}}$ is less than $V_{\text{MRT}}$ (Manual Reset Threshold) RESET/RESET is engaged.
B1	1	V <sub>CC</sub>	Power Supply input.
C1	10	RESET	Reset Logic Output. Pulses low for $t_{RP}$ (Reset Timeout Period) when triggered, and stays low whenever $V_{CC}$ is below the reset threshold or when $\overline{MR}$ is below $V_{MRT}$ . It remains low for $t_{RP}$ after either $V_{CC}$ rises above the reset threshold, or after $\overline{MR}$ input rises above $V_{MRT}$ (LM3704 only).
		RESET	Reset Logic Output. RESET is the inverse of RESET (LM3705 only).
C2	8	PFO	Power-Fail Logic Output. When PFI is below V <sub>PFT</sub> , PFO goes low; otherwise, PFO remains high.
C3	7	ĪLO	Low-Line Logic Output. Early Power-Fail warning output. Low when V <sub>CC</sub> falls below V <sub>LLOT</sub> (Low-Line Output Threshold). This output can be used to generate an NMI (Non-Maskable Interrupt) to provide an early warning of imminent power-failure.
B3	5	GND	Ground reference for all signals.
A3	4, 6	NC	No Connect.
A2	3	PFI	Power-Fail Comparator Input. When PFI is less than V <sub>PFT</sub> (Power-Fail Reset Threshold), the PFO goes low; otherwise, PFO remains high.
B2	9	NC	No Connect. Test input used at factory only. Leave floating.

## **Block Diagram**



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### **Ordering Information**



<sup>\* =</sup> available upon request. Contact National Semiconductor

10136904

#### LM3704/LM3705

		Reset Timeout	Pac	Pookogo	
Part Number	Output	Period	MSOP	micro SMD	- Package Marking
LM3704XCBP-308	totem-pole	200ms		х	%%l4
LM3704XCBPX-308	totem-pole	200ms		х	%%l4
LM3704XCMM-308	totem-pole	200ms	х		R35B
LM3704XCMMX-308	totem-pole	200ms	х		R35B
LM3705XCBP-308	totem-pole	200ms		х	%%I5
LM3705XCBPX-308	totem-pole	200ms		х	%%I5
LM3705XCMM-308	totem-pole	200ms	х		R36B
LM3705XCMMX-308	totem-pole	200ms	х		R36B

<sup>%%</sup> is the datecode and will vary with time.

### **Table Of Functions**

Part Number	Active Low Reset	Active High Reset	Output (X = totem-pole) (Y = open-drain)	Reset Timeout Period	Manual Reset	Power Fail Comparator	Low Line Output
LM3704	х		X, Y*	Customized	х	х	х
LM3705		х	Х	Customized	х	х	х

<sup>\* =</sup> available upon request. Contact National

<sup>\*</sup>For other voltages between 2.2V and 5.0V, please contact National Semiconductor sales office.

### Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage ( $V_{CC}$ ) -0.3V to 6.0V

All Other Inputs -0.3V to  $V_{CC}$  + 0.3V

ESD Ratings (Note 2)

Human Body Model 1.5kV Machine Model 150V Power Dissipation

(Note 3)

## Operating Ratings (Note 1)

Temperature Range  $-40^{\circ}\text{C} \le \text{T}_{\text{J}} \le 85^{\circ}\text{C}$ 

#### LM3704/LM3705 Series Electrical Characteristics

Limits in the standard typeface are for  $T_J = 25^{\circ}C$  and limits in **boldface type** apply over full operating range. Unless otherwise specified:  $V_{CC} = +2.2V$  to 5.5V.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
POWER S	JPPLY					
V <sub>CC</sub>	Operating Voltage	LM3704	1.0		5.5	V
	Range: V <sub>CC</sub>	LM3705	1.2		5.5	7 °
I <sub>cc</sub>	V <sub>CC</sub> Supply Current	All inputs = V <sub>CC</sub> ; all outputs floating		28	50	μA
RESET TH	RESHOLD					•
V <sub>RST</sub>	Reset Threshold	V <sub>CC</sub> falling	-0.5		+0.5	
			-2	V <sub>RST</sub>	+2	%
		V <sub>CC</sub> falling: T <sub>A</sub> = 0°C to 70°C	-1.5	] [	+1.5	
V <sub>RSTH</sub>	Reset Threshold Hysteresis			0.0032•V <sub>RST</sub>		mV
t <sub>RP</sub>	Reset Timeout	Reset Timeout Period = A	1	1.4	2	
	Period	Reset Timeout Period = B	20	28	40	mo
		Reset Timeout Period = C	140	200	280	ms
		Reset Timeout Period = D	1120	1600	2240	
t <sub>RD</sub>	V <sub>CC</sub> to Reset Delay	V <sub>CC</sub> falling at 1mV/μs		20		μs
RESET (LI	Л3705)					•
V <sub>OL</sub>	RESET	$V_{CC} > 2.25V, I_{SINK} = 900\mu A$			0.3	
		V <sub>CC</sub> > 2.7V, I <sub>SINK</sub> = 1.2mA			0.3	\ \ \
		V <sub>CC</sub> > 4.5V, I <sub>SINK</sub> = 3.2mA			0.4	7
V <sub>OH</sub>	RESET	$V_{CC} > 1.2V$ , $I_{SOURCE} = 50\mu A$	0.8 V <sub>CC</sub>			
		V <sub>CC</sub> > 1.8V, I <sub>SOURCE</sub> = 150μA	0.8 V <sub>cc</sub>			7
		$V_{CC} > 2.25V, I_{SOURCE} = 300\mu A$	0.8 V <sub>CC</sub>			\ \ \
		$V_{\rm CC} > 2.7 \text{V}$ , $I_{\rm SOURCE} = 500 \mu \text{A}$	0.8 V <sub>CC</sub>			7
		$V_{\rm CC} > 4.5 \text{V}$ , $I_{\rm SOURCE} = 800 \mu \text{A}$	V <sub>cc</sub> - 1.5V			
I <sub>LKG</sub>	Output Leakage	V <sub>RESET</sub> = 5.5V			1.0	μA
	Current					
RESET (LI	Л3704)					'
V <sub>OL</sub>	RESET	$V_{CC} > 1.0V, I_{SINK} = 50\mu A$			0.3	
		$V_{CC} > 1.2V$ , $I_{SINK} = 100\mu A$			0.3	7
		$V_{CC} > 2.25V$ , $I_{SINK} = 900\mu A$			0.3	7
		V <sub>CC</sub> > 2.7V, I <sub>SINK</sub> = 1.2mA			0.3	7 ,,
		V <sub>CC</sub> > 4.5V, I <sub>SINK</sub> = 3.2mA			0.4	- V
V <sub>OH</sub>	RESET	$V_{CC} > 2.25V, I_{SOURCE} = 300\mu A$	0.8 V <sub>CC</sub>			7
		$V_{CC} > 2.7V$ , $I_{SOURCE} = 500\mu A$	0.8 V <sub>CC</sub>			7
		V <sub>CC</sub> > 4.5V, I <sub>SOURCE</sub> = 800μA	V <sub>cc</sub> - 1.5V			7

### LM3704/LM3705 Series Electrical Characteristics (Continued)

Limits in the standard typeface are for  $T_J = 25^{\circ}C$  and limits in **boldface type** apply over full operating range. Unless otherwise specified:  $V_{CC} = +2.2V$  to 5.5V.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
PFI/MR			•			•
$V_{PFT}$	PFI Input Threshold		1.200	1.225	1.250	V
$V_{MRT}$	MR Input	MR, Low			0.8	V
	Threshold	MR, High	2.0			
V <sub>PFTH</sub> / V <sub>MRTH</sub>	PFI/MR Threshold Hysteresis	PFI/ $\overline{MR}$ falling: $V_{CC} = V_{RST MAX}$ to 5.5V		0.0032•V <sub>RST</sub>		mV
I <sub>PFI</sub>	Input Current (PFI only)		-75		75	nA
$R_{MR}$	MR Pull-up Resistance		35	56	75	kΩ
t <sub>MD</sub>	MR to Reset Delay			12		μS
t <sub>MR</sub>	MR Pulse Width		25			μS
PFO, LLO	1		1			
V <sub>OL</sub>	PFO, LLO Output	$V_{CC} > 2.25V$ , $I_{SINK} = 900\mu A$			0.3	
	Voltage	$V_{CC} > 2.7V$ , $I_{SINK} = 1.2mA$			0.3	
		$V_{CC} > 4.5V$ , $I_{SINK} = 3.2mA$			0.4	V
$V_{OH}$		$V_{CC} > 2.25V$ , $I_{SOURCE} = 300\mu A$	0.8 V <sub>CC</sub>			v
		$V_{CC} > 2.7V$ , $I_{SOURCE} = 500\mu A$	0.8 V <sub>CC</sub>			
		$V_{CC} > 4.5V$ , $I_{SOURCE} = 800\mu A$	V <sub>CC</sub> - 1.5V			
LLO OUTF	PUT					
$V_{LLOT}$	LLO Output		1.01•V <sub>RST</sub>	1.02•V <sub>RST</sub>	1.03•V <sub>RST</sub>	V
	Threshold (V <sub>LLO</sub> – V <sub>RST</sub> , V <sub>CC</sub> falling)					
$V_{LLOTH}$	Low-Line Comparator Hysteresis			0.0032•V <sub>RST</sub>		m۷
t <sub>CD</sub>	Low-Line Comparator Delay	V <sub>CC</sub> falling at 1mV/μs		20		μs

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed conditions.

Note 2: The Human Body model is a 100 pF capacitor discharged through a 1.5 k $\Omega$  resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin.

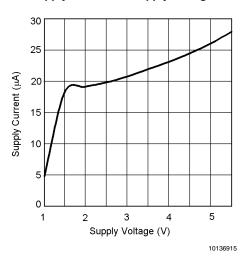
Note 3: The maximum allowable power dissipation is a function of the maximum junction temperature,  $T_J(MAX)$ , the junction-to-ambient thermal resistance,  $\theta_{J-A}$ , and the ambient temperature,  $T_A$ . The maximum allowable power dissipation at any ambient temperature is calculated using:

$$P(MAX) = \frac{T_{J}(MAX) - T_{A}}{\theta_{J-A}}$$

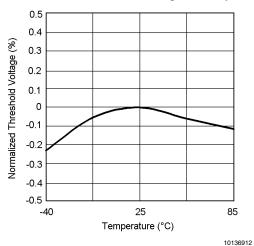
Where the value of  $\theta_{J-A}$  for the MSOP-10 package is 195 C/W in a typical PC board mounting and the micro SMD package is 220 C/W.

### **Typical Performance Characteristics**

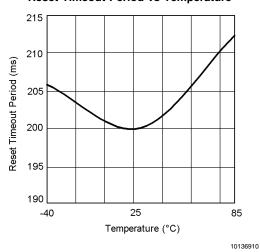
#### Supply Current vs Supply Voltage



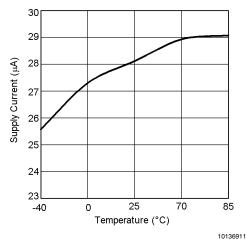
#### Normalized Reset Threshold Voltage vs Temperature



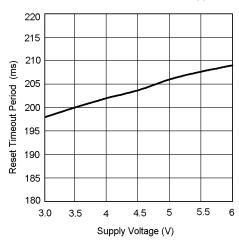
#### **Reset Timeout Period vs Temperature**



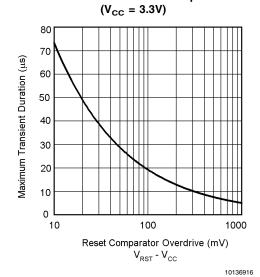
#### 3.3V Supply Current vs Temperature



#### Reset Timeout Period vs V<sub>CC</sub>

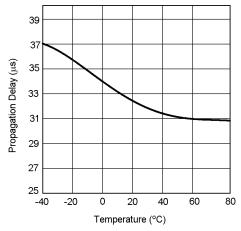


Max. Transient Duration vs Reset Comparator Overdrive



# Typical Performance Characteristics (Continued)

Low-Line Comparator Propagation Delay vs Temperature



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#### **Circuit Information**

#### **Reset Output**

The Reset input of a  $\mu P$  initializes the device into a known state. The LM3704/LM3705 microprocessor supervisory circuits assert a forced reset output to prevent code execution errors during power-up, power-down, and brownout conditions.

RESET is guaranteed valid for  $V_{CC} > 1V$ . Once  $V_{CC}$  exceeds the reset threshold, an internal timer maintains the output for the reset timeout period. After this interval, reset goes high. The LM3704 offers an active-low  $\overline{RESET}$ ; The LM3705 offers an active-high RESET.

Any time  $V_{\rm CC}$  drops below the reset threshold (such as during a brownout), the reset activates. When  $V_{\rm CC}$  again rises above the reset threshold, the internal timer starts. Reset holds until  $V_{\rm CC}$  exceeds the reset threshold for longer than the reset timeout period. After this time, reset releases.

The Manual Reset input  $(\overline{MR})$  will initiate a forced reset also. See the *Manual Reset Input* section.

#### **Reset Threshold**

The LM3704/LM3705 family is available with a reset voltage of 3.08V. Other reset thresholds in the 2.20V to 5.0V range, in steps of 10 mV, are available; contact National Semiconductor for details.

#### Manual Reset Input (MR)

Many  $\mu P$ -based products require a manual reset capability, allowing the operator to initiate a reset. The  $\overline{MR}$  input is fully debounced and provides an internal 56 k $\Omega$  pull-up. When the  $\overline{MR}$  input is pulled below  $V_{MRT}$  (1.225V) for more than 25  $\mu s$ , reset is asserted after a typical delay of 12  $\mu s$ . Reset remains active as long as  $\overline{MR}$  is held low, and releases after the reset timeout period expires after  $\overline{MR}$  rises above  $V_{MRT}$ . Use  $\overline{MR}$  with digital logic to assert or to daisy chain supervisory circuits. It may be used as another low-line comparator by adding a buffer.

#### Power-Fail Comparator (PFI/PFO)

The PFI is compared to a 1.225V internal reference,  $V_{PFT}$ . If PFI is less than  $V_{PFT}$ , the Power Fail Output  $\overline{PFO}$  drops low. The power-fail comparator signals a falling power supply, and is driven typically by an external voltage divider that senses either the unregulated supply or another system

supply voltage. The voltage divider generally is chosen so the voltage at PFI drops below  $V_{\rm PFT}$  several milliseconds before the main supply voltage drops below the reset threshold, providing advanced warning of a brownout.

The voltage threshold is set by  $R_1$  and  $R_2$  and is calculated as follows:

$$V_{PFT} = \left(\frac{R1 + R2}{R2}\right) \times 1.225V$$

Note this comparator is completely separate from the rest of the circuitry, and may be employed for other functions as needed.

#### Low-Line Output (LLO)

The low-line output comparator is typically used to provide a non-maskable interrupt to a  $\mu P$  when  $V_{CC}$  begins falling. LLO monitors  $V_{CC}$  and goes low when  $V_{CC}$  falls below  $V_{LLOT}$  (typically 1.02 •  $V_{RST}$ ) with hysteresis of 0.0032 •  $V_{RST}$ .

#### Special Precautions for the micro SMD Package

As with most integrated circuits, the LM3704 and LM3705 are sensitive to exposure from visible and infrared (IR) light radiation. Unlike a plastic encapsulated IC, the micro SMD package has very limited shielding from light, and some sensitivity to light reflected from the surface of the PC board or long wavelength IR entering the die from the side may be experienced. This light could have an unpredictable affect on the electrical performance of the IC. Care should be taken to shield the device from direct exposure to bright visible or IR light during operation.

#### Micro SMD Mounting

The micro SMD package requires specific mounting techniques which are detailed in National Semiconductor Application Note AN-1112. Referring to the section *Surface Mount Technology (SMT) Assembly Considerations*, it should be noted that the pad style which must be used with the 9-pin package is the NSMD (non-solder mask defined) type.

For best results during assembly, alignment ordinals on the PC board may be used to facilitate placement of the micro SMD device.

# **Timing Diagrams**

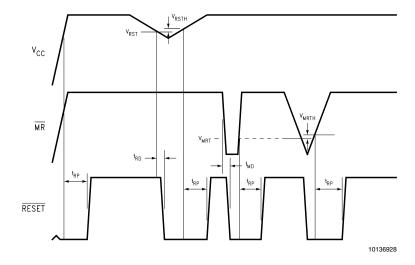


FIGURE 1. LM3704 Reset Time with  $\overline{\text{MR}}$ 

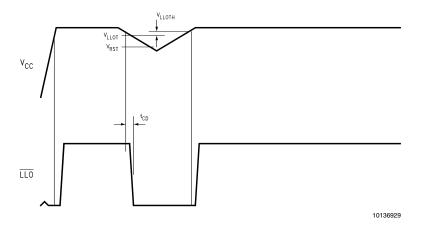


FIGURE 2. LLO Output

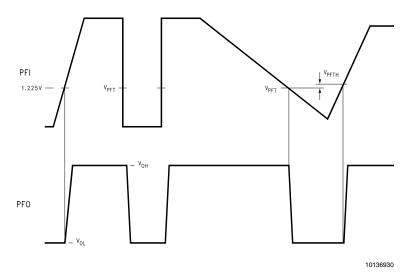
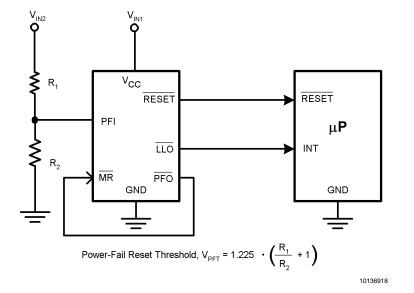


FIGURE 3. PFI Comparator Timing Diagram

# **Typical Application Circuits**



**FIGURE 4. Monitoring Two Critical Supplies** 

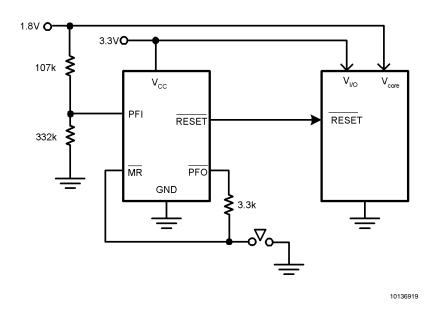


FIGURE 5. Monitoring Two Supplies plus Manual Reset

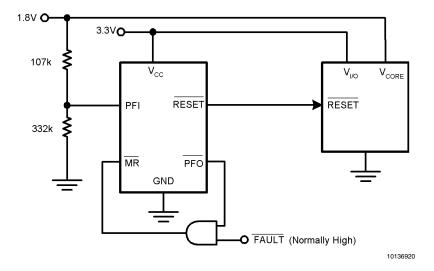
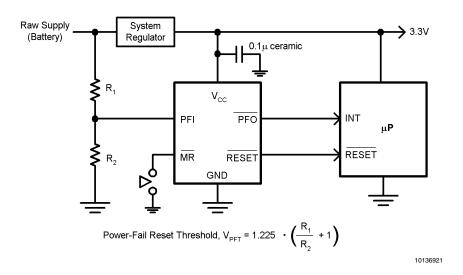


FIGURE 6. Monitoring Dual Supplies plus External Fault Input



Note:  $\overline{\text{MR}}$  input with its 1.225V nominal threshold, may monitor an additional supply voltage. An internal 56 k $\Omega$  pull-up resistor is included on this input.

FIGURE 7. Microprocessor Supervisor with Early Warning Detector

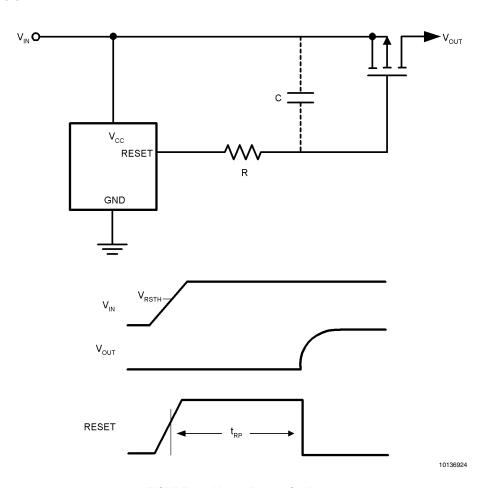


FIGURE 8. LM3705 Power-On Delay

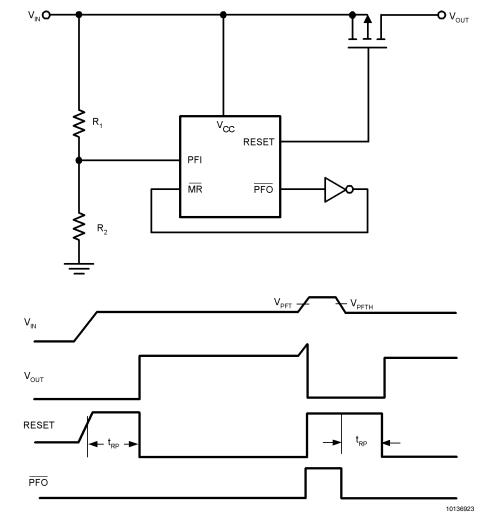


FIGURE 9. LM3705 Power-On Delay with Overvoltage Protection

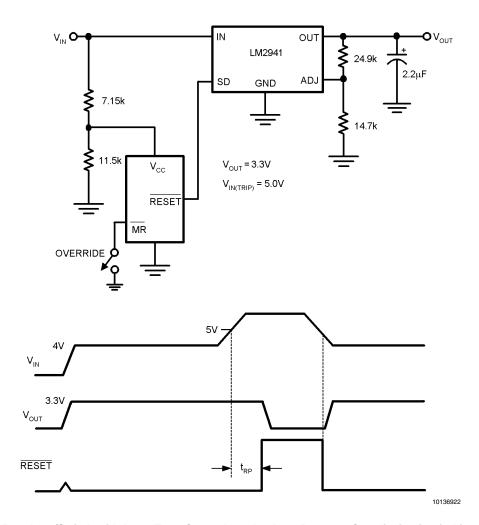


FIGURE 10. Regulator/Switch with Long-Term Overvoltage Lockout Prevents Overdissipation in Linear Regulator

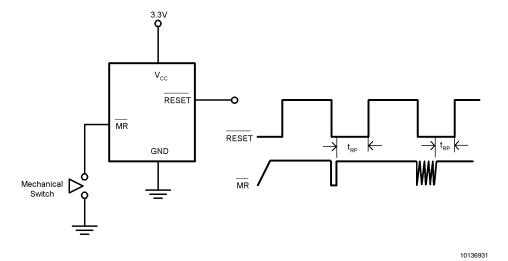
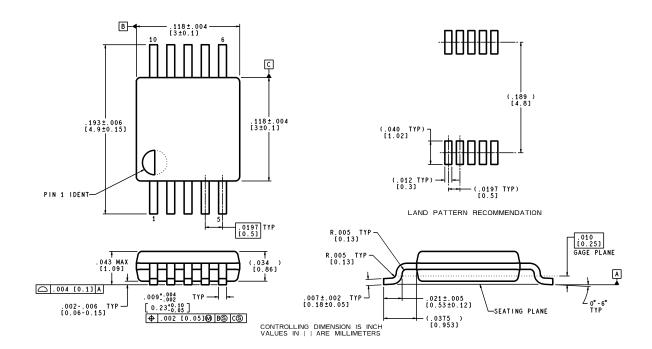


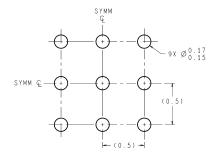
FIGURE 11. Switch Debouncer

# **Physical Dimensions** inches (millimeters) unless otherwise noted



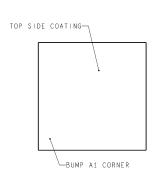
MUB10A (Rev A)

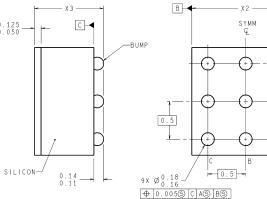
10 Lead MSOP Package NS Package Number MUB10A



DIMENSIONS ARE IN MILLIMETERS

#### LAND PATTERN RECOMMENDATION





NOTES: UNLESS OTHERWISE SPECIFIED

- 1. EPOXY COATING
- 2. 63Sn/37Pb EUTECTIC BUMP
- 3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- 4. PIN 1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION. REMAINING PINS ARE NUMBERED COUNTER CLOCKWISE
- 5. XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT.

6.NO JEDEC REGISTRATION AS OF AUG.1999.

9 bump micro SMD Package **NS Package Number BPA09FFB** The dimensions of X1, X2 and X3 are given below

> X1 = 1.412mmX2 = 1.412mmX3 = 0.850mm

#### LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

SYMM

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BPA09XXX (Rev D)



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